

Cyclic Loading of Nanocrystalline FCC Metals *In Situ* in the TEM

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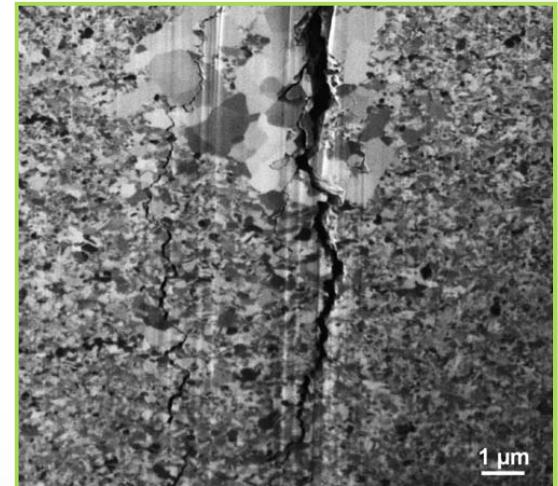
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Motivation

- Fatigue in bulk metals
 - Progressive microstructural change with cyclic loading
 - Often at loads below yield stress
- Fatigue in nc metals
 - Grain boundary migration and grain growth
 - Crack initiation
- What are the underlying mechanisms associated with these phenomena?
 - Pre-deformation microstructure
 - Grain and grain boundary orientations
- *In situ* TEM deformation is a tool capable of investigating these questions.



Execcharter, 2011.



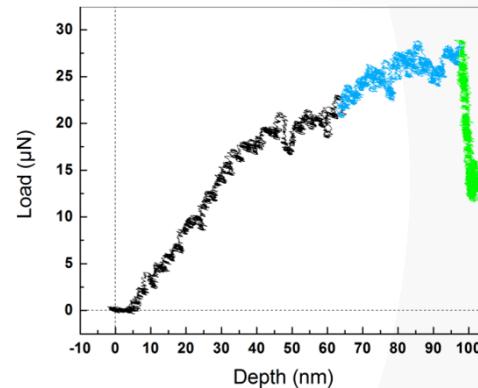
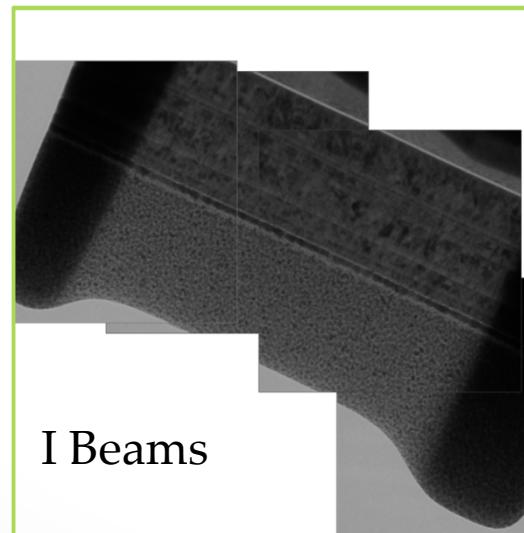
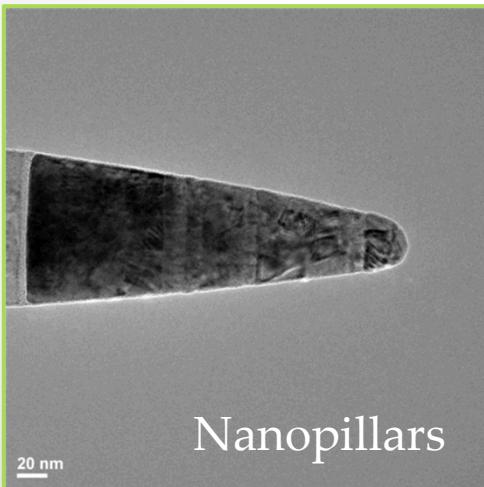
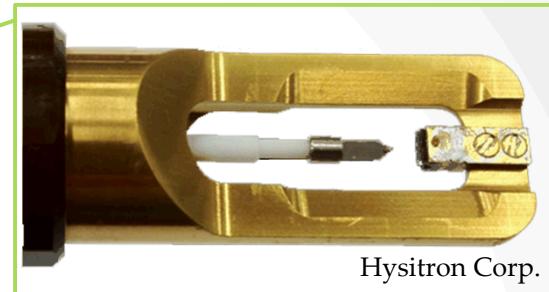
Padilla and Boyce, Exp Mech 2006.

Experimental Tools

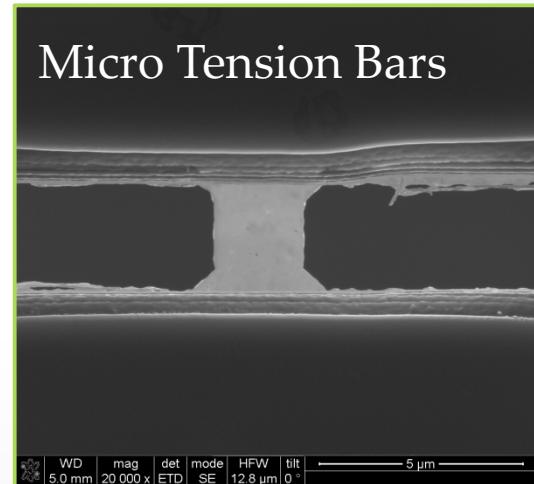


Hysitron PI95 *In Situ* Nanoindentation TEM Holder

- Sub nanometer displacement resolution
- Quantitative force information with μN resolution
- Concurrent real-time imaging by TEM



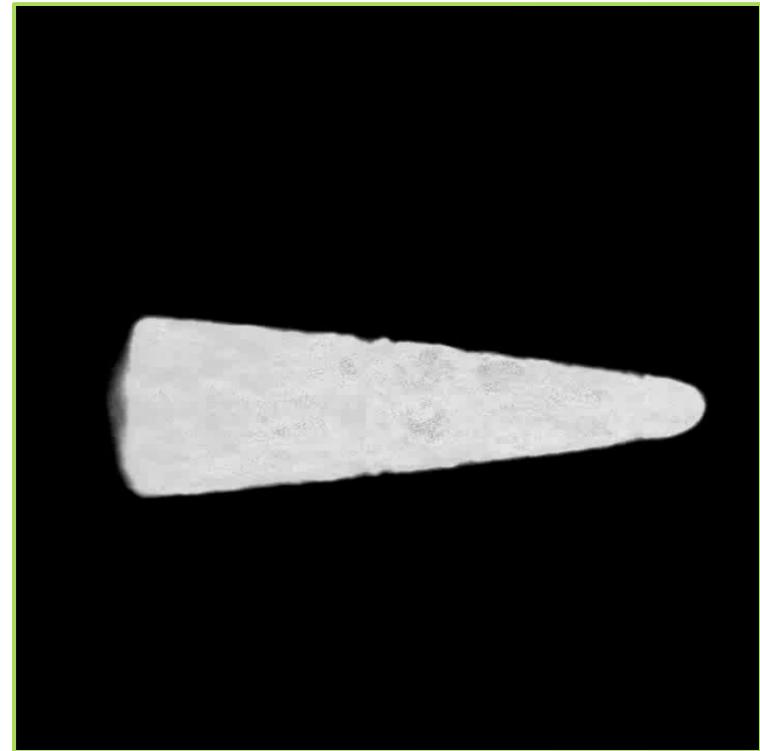
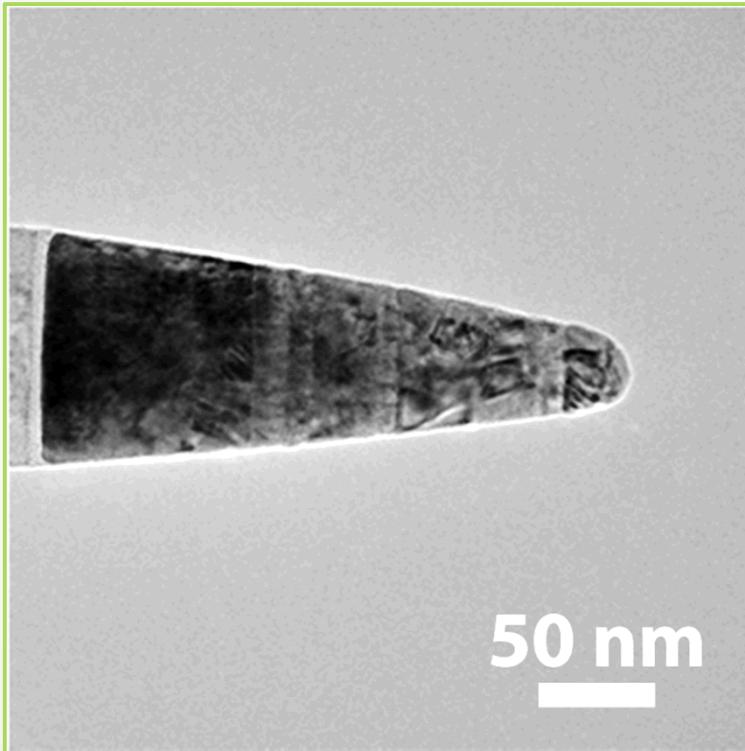
Micro Tension Bars



Nanopillar Fabrication



- FIB-milled from 500 nm PLD Ni on Si
 - ~100 nm base diameter
 - Conical geometry

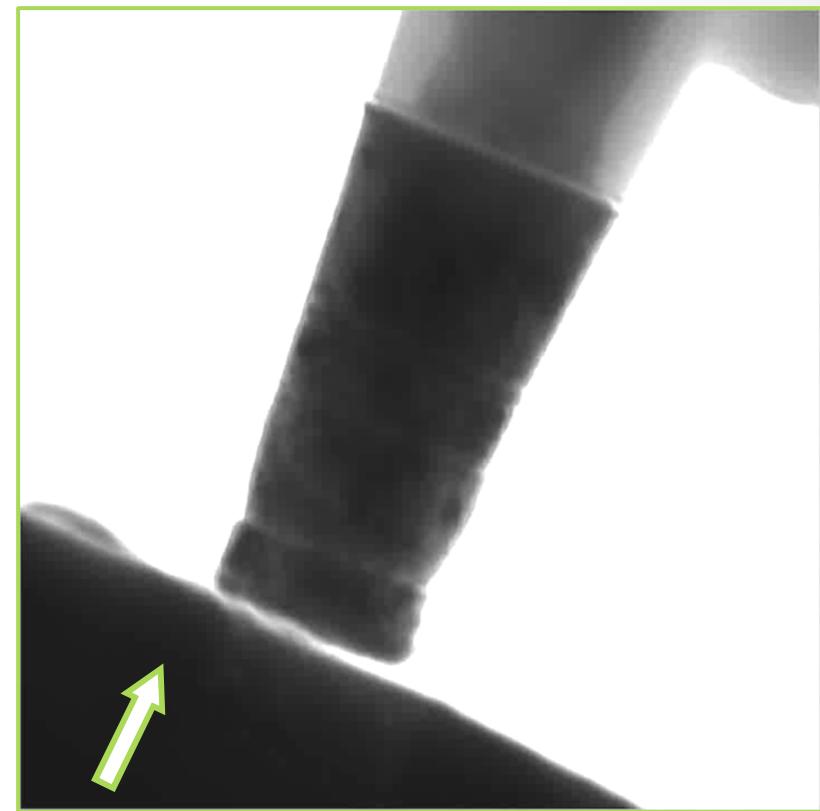
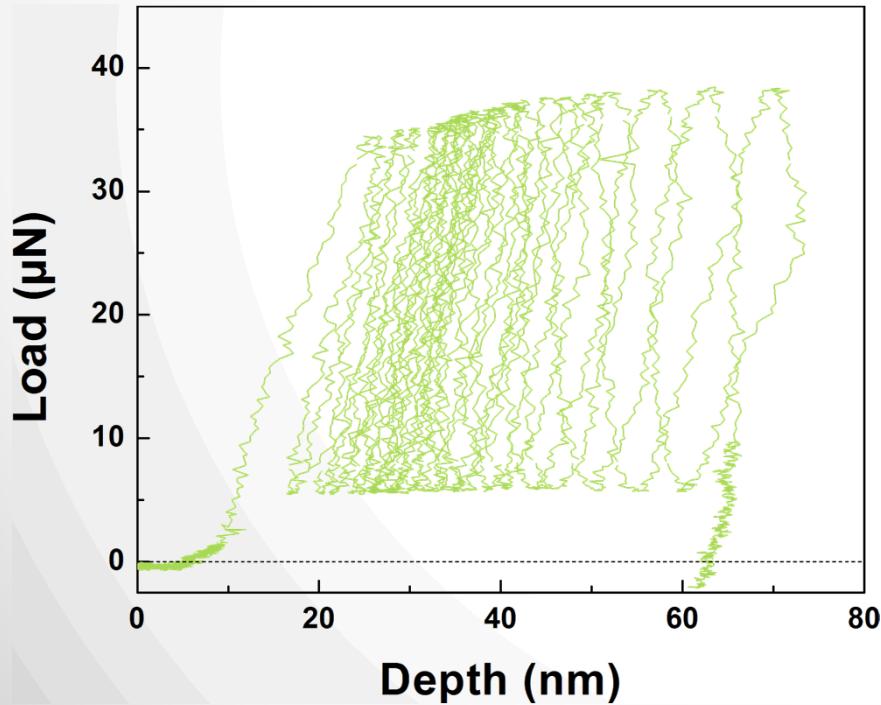


- Mostly electron-transparent, easy geometry for stress calculations
- Small volume, susceptible to vibration and shear

Pillar Compression



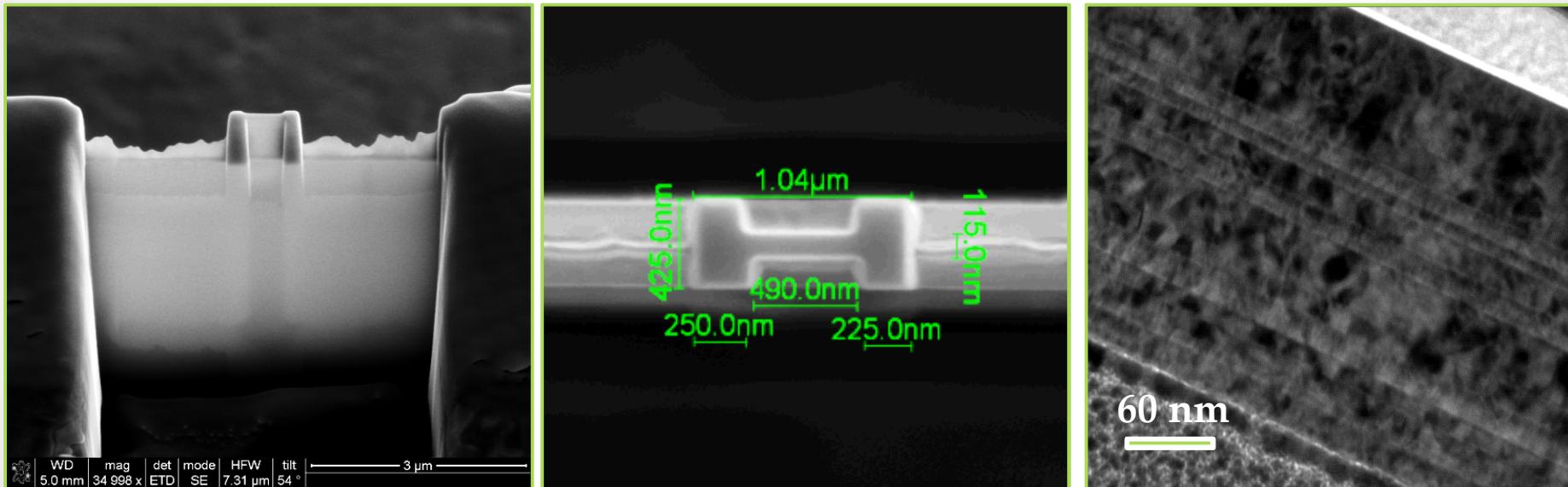
- Cyclic loading with increasing force amplitude
 - After a previous monotonic compression
 - 23 cycles to failure
- Failure initiated at notches



“I-Beam” Fabrication

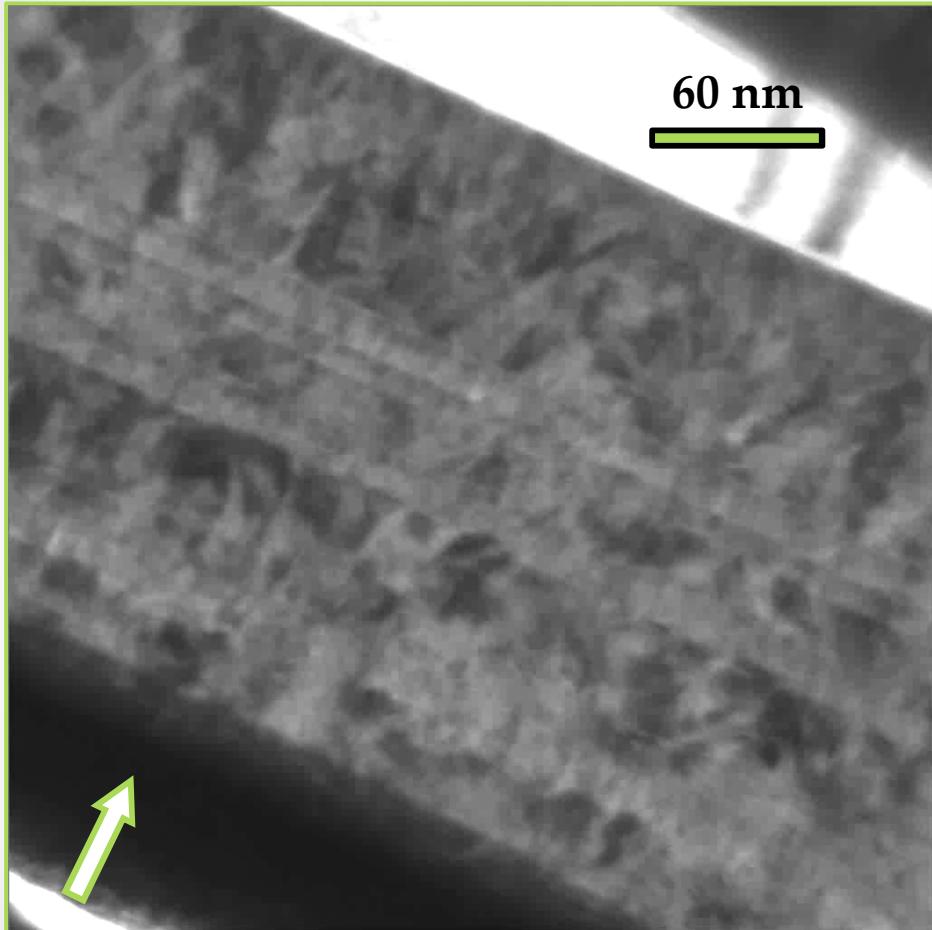


- Wide pillars with transparent center and thicker side supports
- FIB-milled from same 500 nm PLD Ni on Si



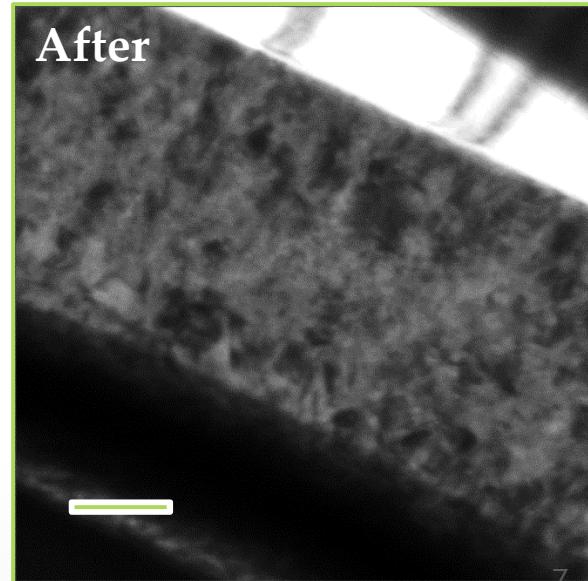
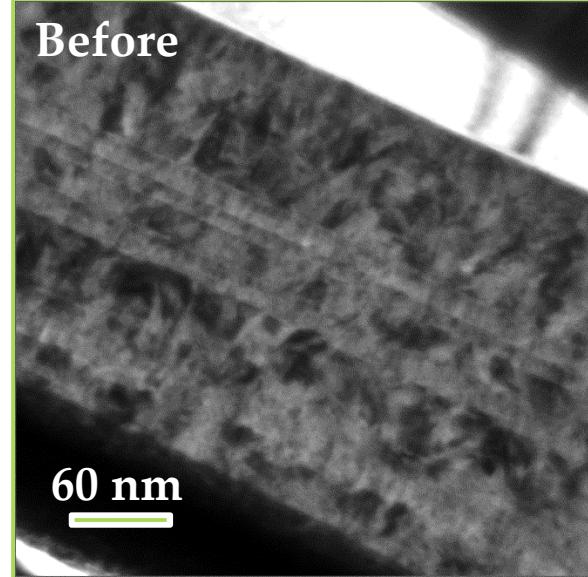
- Enhanced mechanical stability and larger viewable area
- More complicated force-displacement interpretation

I Beam Compression



- Improved visualization
- Evidence of grain growth

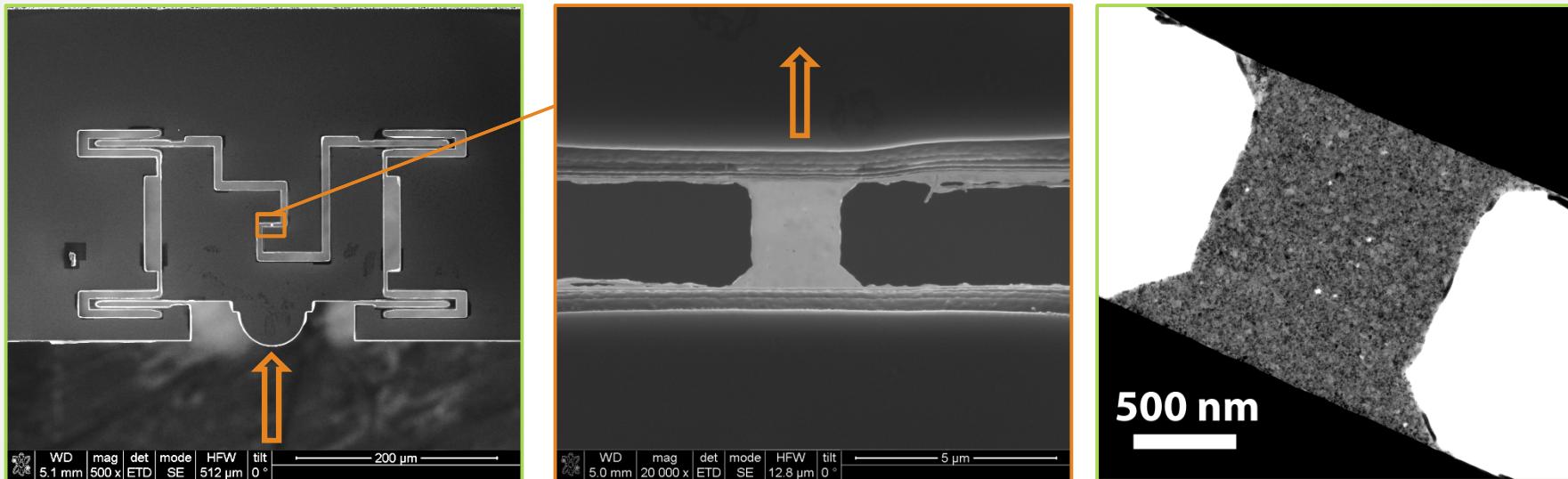
• TMS 2015



Tension Specimen Fabrication

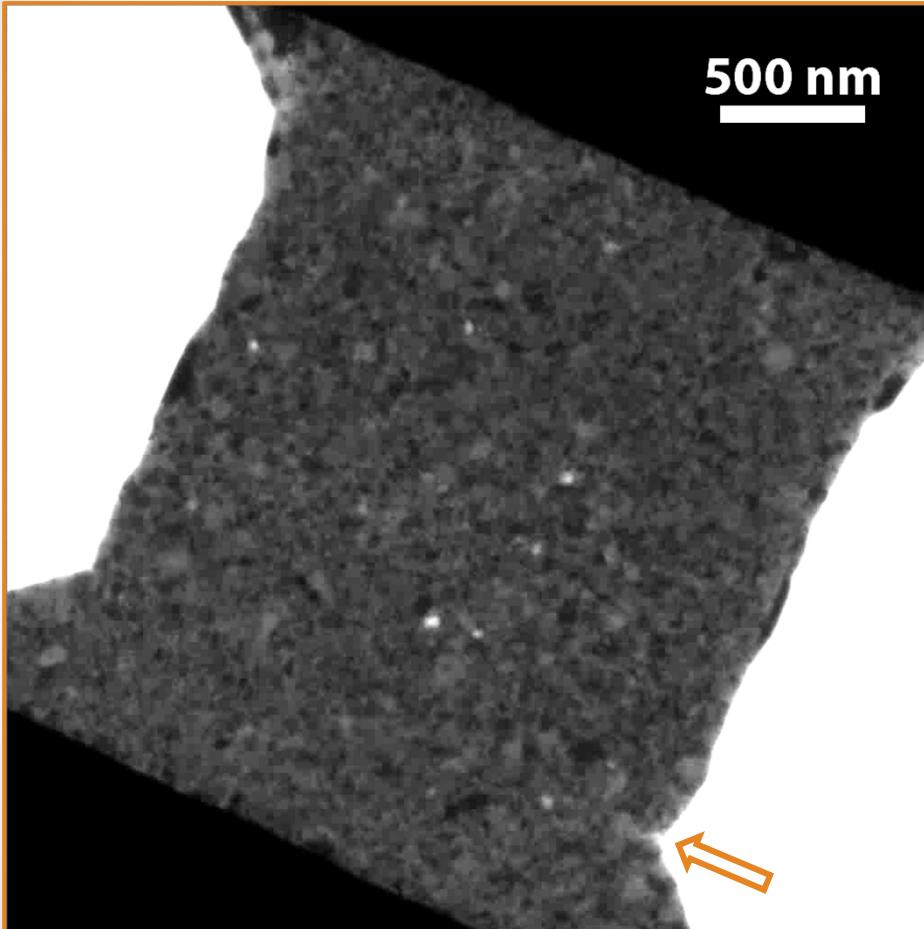


- Hysitron “Push-to-Pull” devices
 - Microfabricated Si test frame
 - Cu film (75 nm) floated onto device, then FIB milled



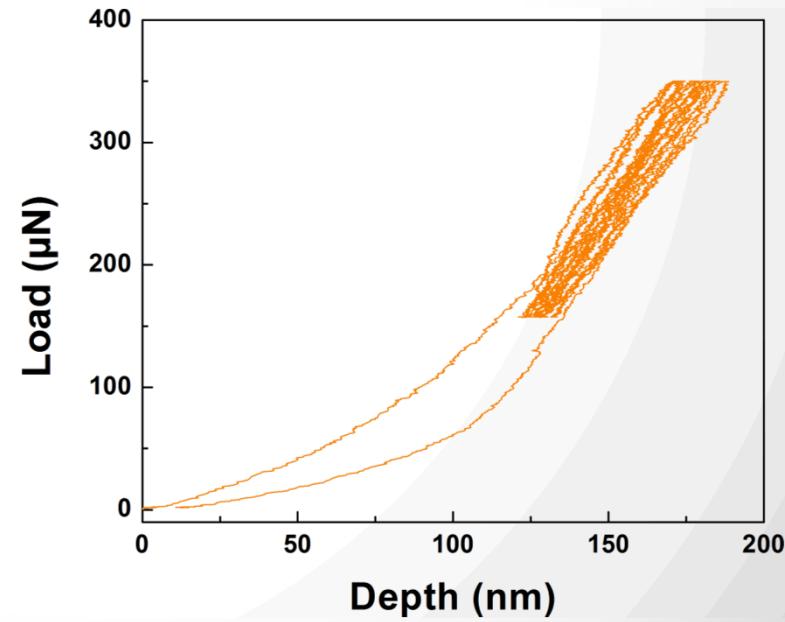
- Nearly pure tension, uniform cross sectional area, stable load frame
- Fragile, sensitive to shape of edges, issues with magnetic materials

Tension Testing



- Slow crack propagation
- Evidence of grain growth

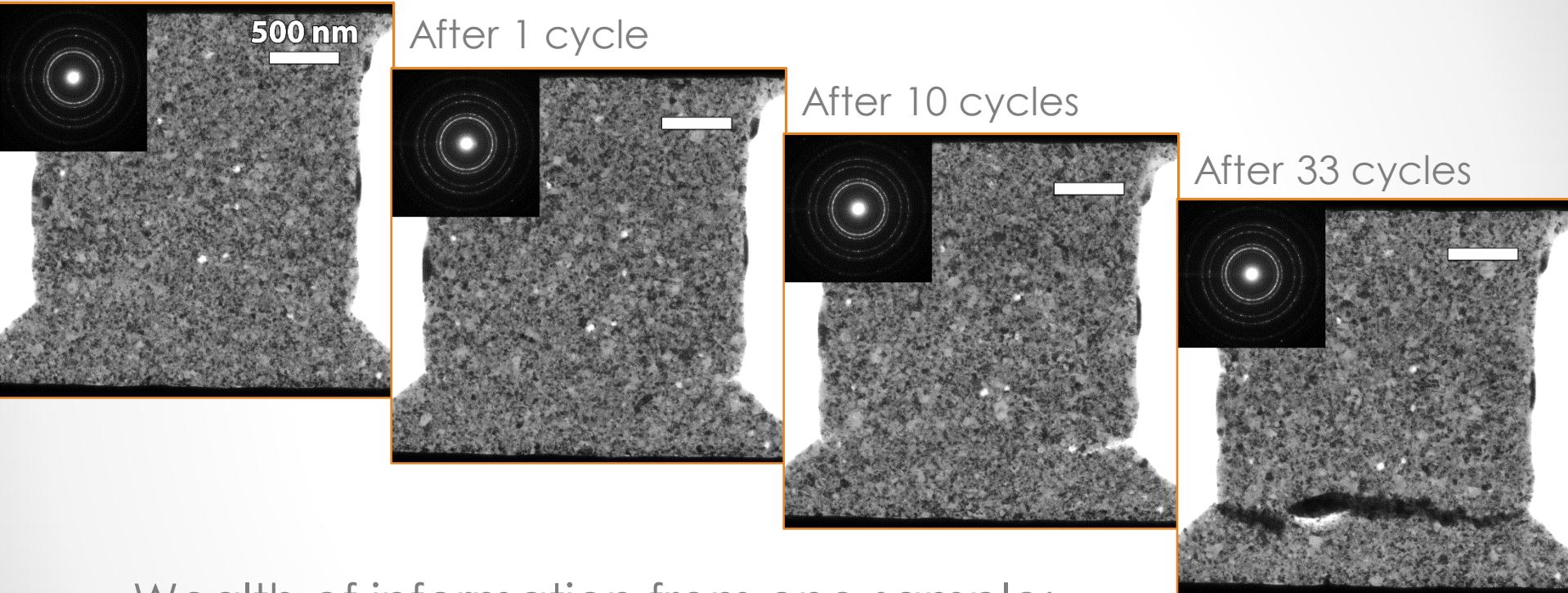
- Cyclic loading:
 - Crack initiated in previous monotonic test
 - 9 cycles to $\sim 87.5\%$ of that load
 - 50 % unloading
 - Slow crack propagation



Cyclic Tension *In Situ*



Before



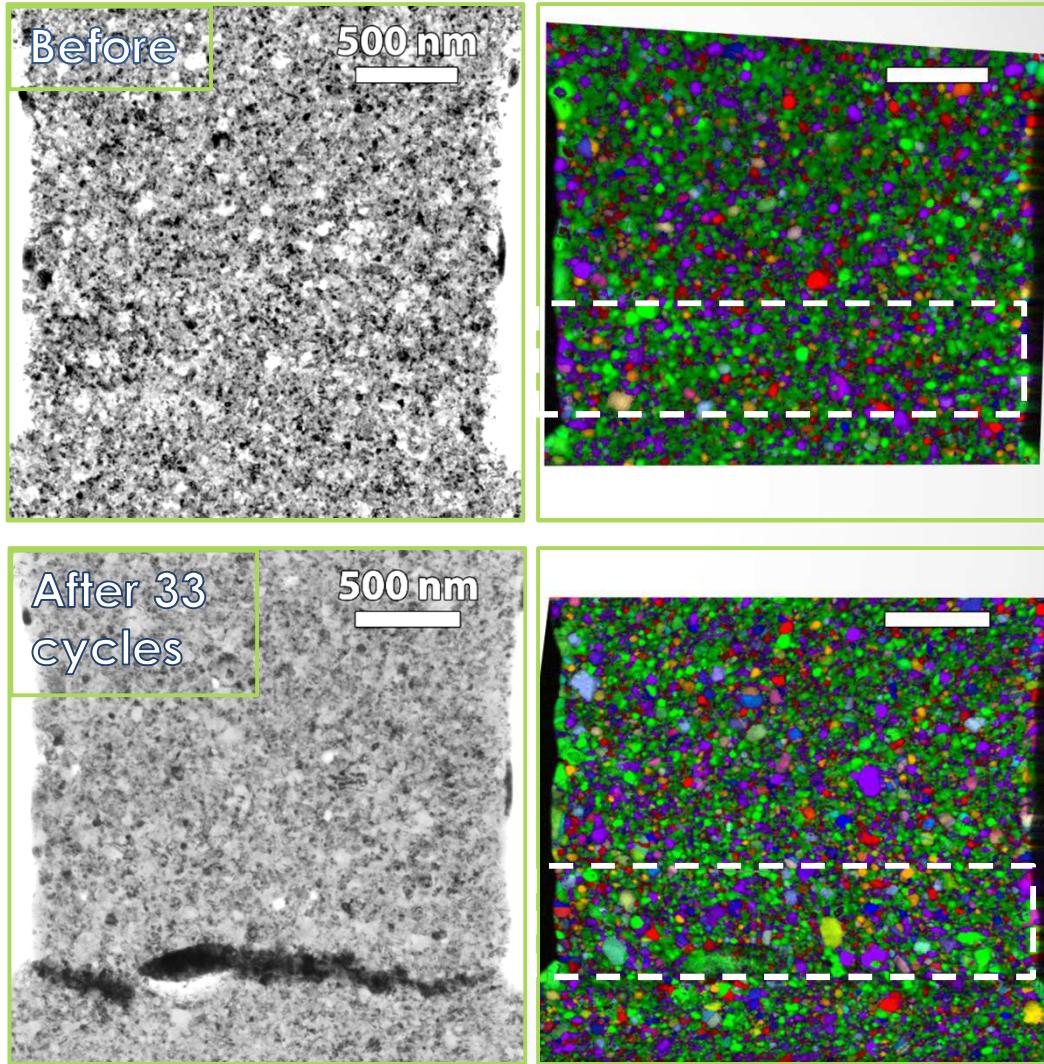
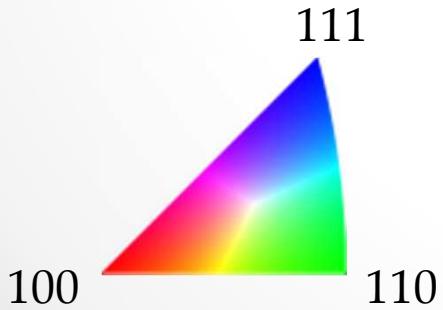
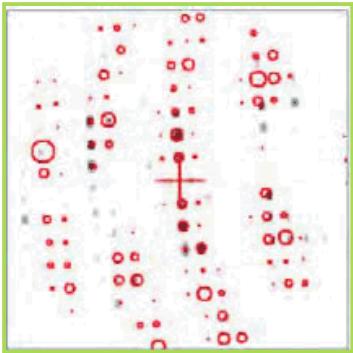
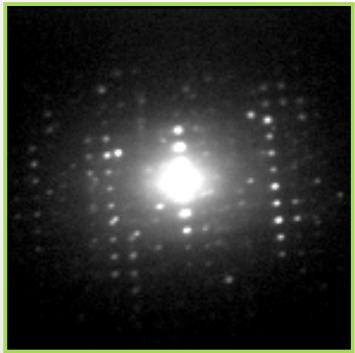
(Post-failure)

- Wealth of information from one sample:
 - Images and electron diffraction at each stage
 - Video and force/displacement during load cycles
- Microstructural change still elusive
 - Difficult to confirm and quantify

Quantifying Microstructural Change

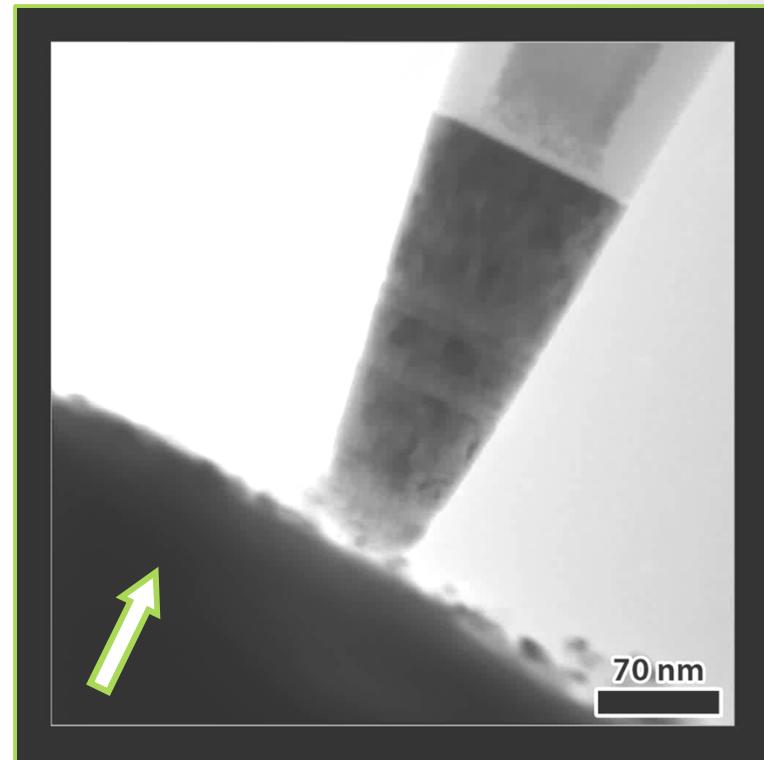
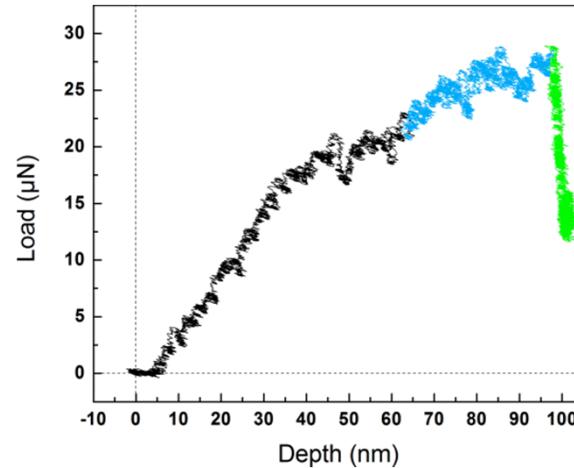
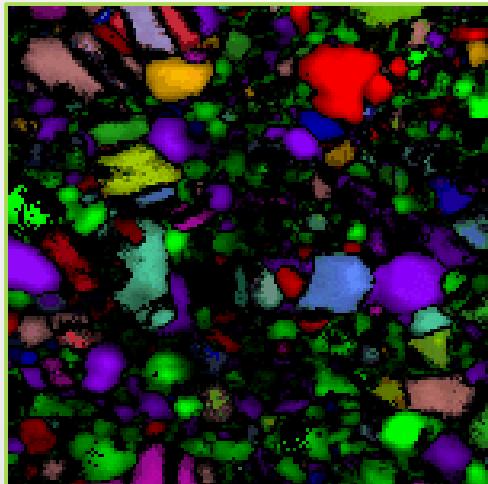


- Combining orientation mapping with deformation
- EBSD-like capability in the TEM
 - Powerful analytical tools available



Summary and Conclusions

- Preliminary low-cycle fatigue tests of nanocrystalline Ni and Cu performed in the TEM
 - Grain growth observed
 - Demonstrated feasibility of these methods



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